

 $\begin{array}{cccc} R & & \vdots & & A0 \\ C & & N \ . \vdots & & \end{array}$

Revision Record					
Control No.	Revision	Description	Date	Drawn	Approved

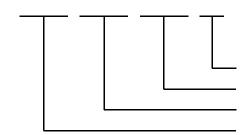
R C A0N .:

TMAX-1770-XXX-M M lded P e I d c

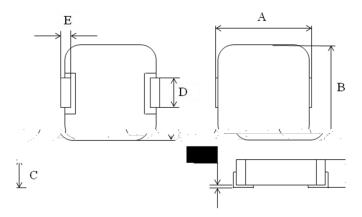
Features

Applications

Product Description



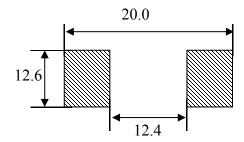
Dimensions



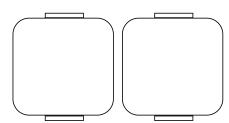
17.5 Max.		
17.15 Max.		
7.0 Max.		
11.8±0.3		
2.5±0.5		
0~0.30		

R C A0 N .:

Recommend Land Pattern Dimensions



Marking



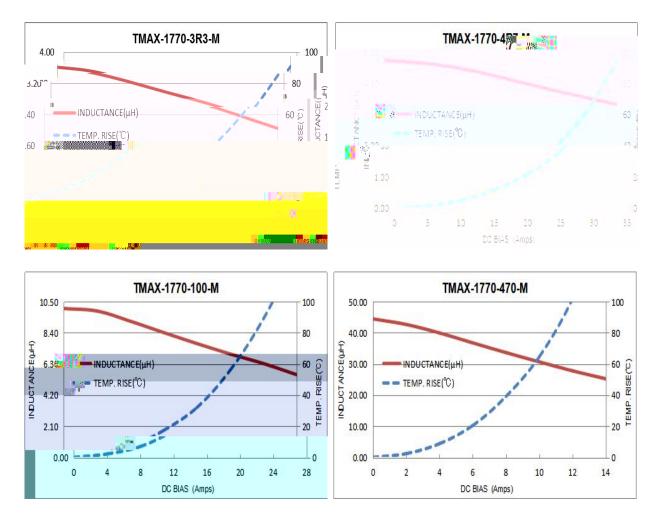
I a : 0.1 H

R : A0 C N ::

Notes:

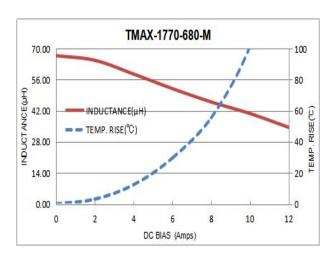
: (),

Inductance and Temperature Rise vs. DC Current





R C A0 N .:



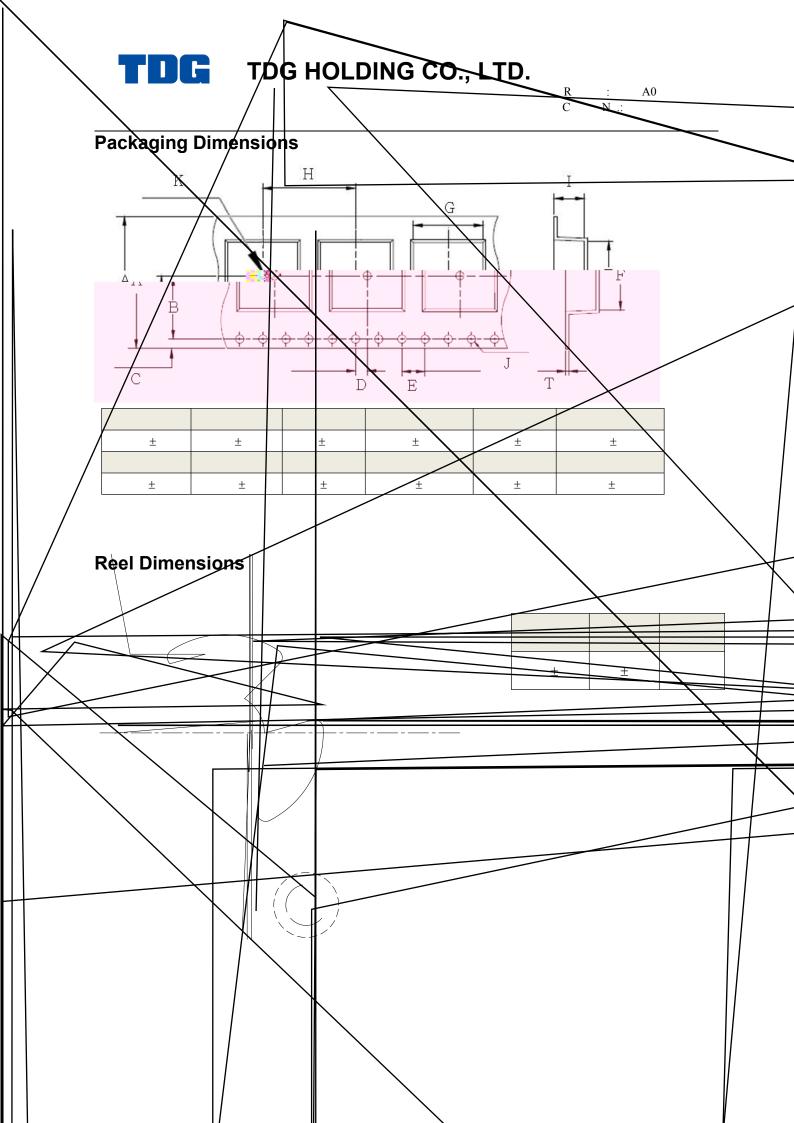
Reliability:

Item	Test Method	Specification and Requirement
	± ± °C ±	
		±

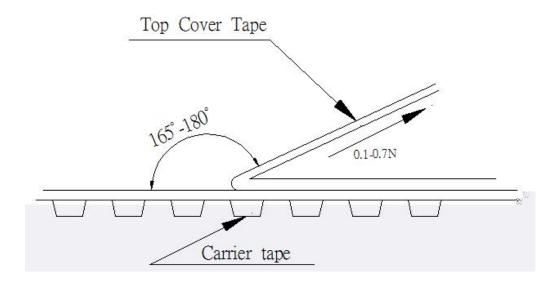


Reliability:

Item	Test Method	Specification and Requirement
	$\begin{array}{cccccccccccccccccccccccccccccccccccc$	
	±	±
	±	
	±	
	±	



Peeling of top cover tape





R A0 C $N\ \, .:$

Reflow Profile

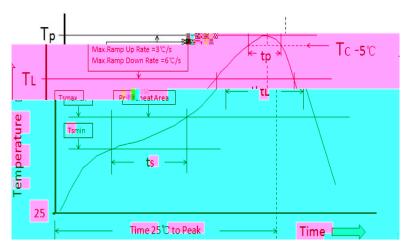


Table1-StandardSnPb Solder(Tc)

Package Thickness	Volume mm³ <350	Volume mm³ ≧350	
<	°C	°C	
All	°C	°C	

Table2-Lead(Pb)Free Solder(Tc)

Package Thickness	Volume mm³ <350	Volume mm³ 350-2000	Volume mm³ >2000
<	$^{\circ}$	℃	$^{\circ}$
	$^{\circ}$	°C	$^{\circ}$
	$^{\circ}$	°C	$^{\circ}$

Reference JDEC J-STD-020(latest revision)

Profile Feature	Standard SnPb solder	Lead(Pb) Free Solder
	$^{\circ}$	$^{\circ}$
	$^{\circ}$	°C
	$^{\circ}$	°C
	${\mathbb C}$	°C
°C		
	$^{\circ}$	$^{\circ}$
C		



 $\begin{array}{cccc} R & & \vdots & & A0 \\ C & & N \ . \vdots & & \end{array}$

Numbers of taping

Label marking

Production Label

Shipping Label

Care note for use

> Storage Condition

> Use Temperature



R : A0 C N .:

Care note for Safety